

MM74HC594 8-Bit Shift Register with Output Registers

General Description

This high speed shift register utilizes advanced silicon-gate CMOS technology. This device possesses the high noise immunity and low power consumption of standard CMOS integrated circuits, as well as the ability to drive 15 LS-TTL loads

This device contains an 8-bit Serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. Separate clocks and direct overriding clears are provided for both the shift register and the storage register. The shift register has a direct-overriding clear, serial input, and serial output (standard) pins for cascading. Both the shift register and storage register use positive-edge triggered clocks. If both clocks are connected together, the shift register state will always be one clock pulse ahead of the storage register.

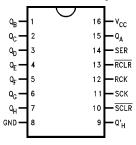
The 54HC/74HC logic family is speed, function, and pin-out compatible with the standard 54LS/74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to $V_{\rm CC}$ and ground.

Features

- Low quiescent current: 80 µA maximum (74HC Series)
- Low input current: 1 µA maximum
- 8-bit serial-in, parallel-out shift register with storage
- Wide operating voltage range: 2V-6V
- Cascadable
- Shift register has direct clear
- Guaranteed shift frequency: DC to 30 MHz

Connection Diagram

Dual-In-Line Package



TL/F/10915-1 **Top View**

Order Number MM74HC594 See NS Package Number N16E

Truth Table

RCK	SCK	SCLR	RCLR	Function
Χ	Х	Х	L	Storage Register cleared
Χ	Х	L	Х	Shift Register cleared Q'H=0
Х	1	Н	Н	Shift Register clocked $Q_N = Q_{n-1}, Q_0 = SER$
1	Х	Н	Н	Contents of Shift Register transferred to output latches

Absolute Maximum Ratings (Notes 1 & 2) Supply Voltage (V_{CC}) -0.5 to +7.0V DC Input Voltage (V_{IN}) $-\,1.5$ to $V_{\hbox{\footnotesize CC}}\,+\,1.5V$ DC Output Voltage (V_{OUT}) -0.5 to $V_{\mbox{\footnotesize CC}}\!+\!0.5\mbox{\footnotesize V}$ Clamp Diode Current (I_{IK}, I_{OK}) $\pm\,20~mA$ DC Output Current, per pin (I_{OUT}) \pm 35 mA DC V_{CC} or GND Current, per pin (I_{CC}) $\pm\,70~mA$ $-65^{\circ}\text{C to } + 150^{\circ}\text{C}$ Storage Temperature Range (T_{STG}) Power Dissipation (P_D) (Note 3) 600 mW S.O. Package only 500 mW Lead Temp. (T_L) (Soldering 10 seconds) 260°C

Operating Conditions						
	Min	Max	Units			
Supply Voltage (V _{CC})	2	6	V			
DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V			
Operating Temp. Range (T _A) MM74HC	-40	+85	°C			
Input Rise or Fall Times		1000				
(t_r, t_f) $V_{CC} = 2.0V$		1000	ns			
$V_{CC} = 4.5V$		500	ns			
$V_{CC} = 6.0V$		400	ns			

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	v _{cc}	T _A = 25°C		74HC T _A = -40 to 85°C	Units
				Typ Gua		aranteed Limits	
V _{IH}	Minimum High Level Input Voltage		2.0V 4.5V 6.0V		1.5 3.15 4.2	1.5 3.15 4.2	V V V
V _{IL}	Maximum Low Level Input Voltage		2.0V 4.5V 6.0V		0.5 1.35 1.8	0.5 1.35 1.8	V V V
V _{OH}	Minimum High Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT} \le 20 \mu A$	2.0V 4.5V 6.0V	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	V V V
	Q' _H	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $\begin{vmatrix} I_{OUT} \end{vmatrix} \le 4.0 \text{ mA}$ $\begin{vmatrix} I_{OUT} \end{vmatrix} \le 5.2 \text{ mA}$	4.5V 6.0V	4.2 5.2	3.98 5.48	3.84 5.34	V
	Q _A thru Q _H	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $\begin{vmatrix} I_{OUT} \end{vmatrix} \le 6.0 \text{ mA}$ $\begin{vmatrix} I_{OUT} \end{vmatrix} \le 7.8 \text{ mA}$	4.5V 6.0V	4.2 5.7	3.98 5.48	3.84 5.34	V
V _{OL}	Maximum Low Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT} \le 20 \mu A$	2.0V 4.5V 6.0V	0 0 0	0.1 0.1 0.1	0.1 0.1 0.1	V V V
	Q' _H	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $\begin{vmatrix} I_{OUT} \end{vmatrix} \le 4 \text{ mA}$ $\begin{vmatrix} I_{OUT} \end{vmatrix} \le 5.2 \text{ mA}$	4.5V 6.0V	0.2 0.2	0.26 0.26	0.33 0.33	V
	Q _A thru Q _H	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $\begin{vmatrix} I_{OUT} \end{vmatrix} \le 6.0 \text{ mA}$ $\begin{vmatrix} I_{OUT} \end{vmatrix} \le 7.8 \text{ mA}$	4.5V 6.0V	0.2 0.2	0.26 0.26	0.33 0.33	V
I _{IN}	Maximum Input Current	V _{IN} =V _{CC} or GND	6.0V		±0.1	±1.0	μΑ
Icc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		8.0	80	μΑ

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: -12 mW/°C from 65°C to 85°C; ceramic "J" package: -12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of 5V $\pm 10\%$ the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC}=5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} and I_{CC}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

 $\textbf{AC Electrical Characteristics} \ \ V_{CC} = 2.0 - 6.0 \ V, \ C_L = 50 \ \text{pF}, \ t_f = t_f = 6 \ \text{ns} \ \text{(unless otherwise specified)}$ $T_A = 25^{\circ}C$ $T_A\!=\!-40$ to $85^\circ C$ Symbol **Parameter** Conditions v_{cc} Units Тур **Guaranteed Limits** $C_L = 50 pF$ Maximum Operating 2.0V MHz $f_{\mbox{\scriptsize MAX}}$ 4.8 4.5V 30 24 MHz Frequency 6.0V 35 28 MHz Maximum Propagation Delay $C_L = 50 pF$ 2.0V 150 185 t_{PHL}, t_{PLH} ns from SCK to Q'H 4.5V 30 37 ns 6.0V 25 31 ns Maximum Propagation Delay 2.0V 150 185 $C_L = 50 pF$ t_{PHL}, t_{PLH} ns $C_L = 150 \text{ pF}$ from RCK to QA thru QH 2.0V 200 250 ns 4.5V $C_L = 50 pF$ 30 37 ns $C_L = 150 pF$ 4.5V 40 50 ns 25 $C_L = 50 pF$ 6.0V 31 ns $C_{L} = 150 \text{ pF}$ 6.0V 34 43 ns t_{PHL} , t_{PLH} Maximum Propagation Delay 2.0V 150 185 ns from SCLR to Q'H 4.5V 30 37 ns 6.0V 25 31 ns Maximum Propagation Delay $C_L = 50 \ pF$ 2.0V 125 155 t_{PHL} ns from RCLR to QA thru QH 4.5V 25 31 ns 6.0V 21 26 ns $C_L = 150 pF$ 2.0V 200 250 ns 4.5V 40 50 ns 6.0V 34 43 ns SCLR Low to RCK 2.0V 63 ts 50 ns 4.5V 10 13 ns 6.0V 9 11 ns RCLR High to SCK ts 2.0V 5 5 ns 4.5V 5 5 ns 6.0V 5 5 ns Minimum Setup Time 2.0V 90 110 t_{S} ns from SER to SCK 4.5V 18 22 ns 6.0V 15 19 ns Minimum Removal Time 2.0V 20 20 t_{R} ns from SCLR to SCK 4.5V 10 10 ns 6.0V 10 10 ns Minimum Setup Time from SCK to RCK 2.0V 90 110 t_{S} ns 4.5V 18 22 ns 6.0V 15 19 ns Minimum Hold Time 2.0V 5 5 t_{H} ns SER to SCK 4.5V 5 5 ns 6.0V 5 5 ns

 $\textbf{Note 6:} \ \ C_{PD} \ \ \text{determines the no load dynamic power consumption, P}_D = C_{PD} \ \ V_{CC}^2 \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC}, \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC} \ \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ V_{CC} \ \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ f + I_{CC} \ \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC} \ \ \text{and the no load dynamic current consumption, I}_S = C_{PD} \ \ V_{CC$

 $\overline{\overline{G}} = V_{CC}$ $\overline{G} = GND$ 2.0V

4.5V

6.0V

2.0V

4.5V

6.0V

2.0V

4.5V

6.0V

2.0V

4.5V

6.0V

90

150

5

15

100

20

17

1000

500

400

60

12

10

75

15

13

10

20

125

25

21

1000

500

400

75

15

13

95

19

16

10

20

ns

pF pF

pF

Minimum Pulse Width

Maximum Input Rise and

of SCK or SCLR or

RCK or RCLR

Fall Time, Clock

Maximum Output

 $Q_A - Q_H$

 $Q'_{\underline{H}}$

Rise and Fall Time

Maximum Output

Rise and Fall Time

Power Dissipation Capacitance,

Outputs Enabled (Note 6)

Maximum Input Capacitance

Maximum Output Capacitance

 $t_{\text{W}} \\$

 t_r , t_f

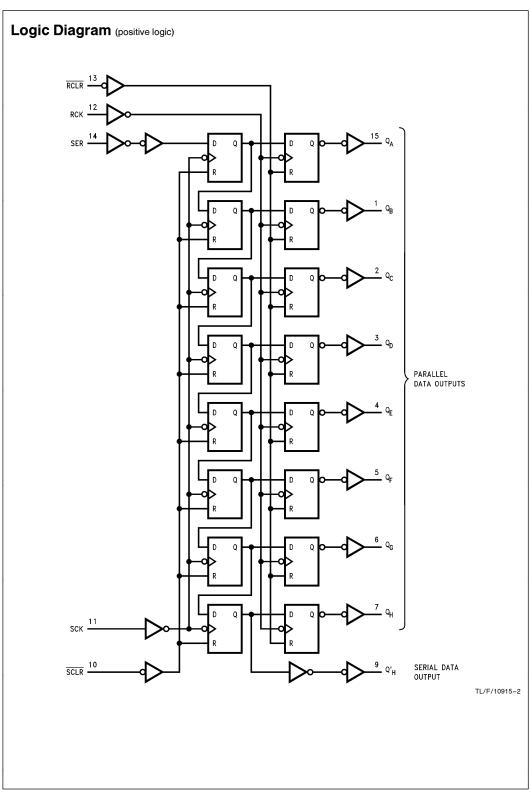
t_{THL}, t_{TLH}

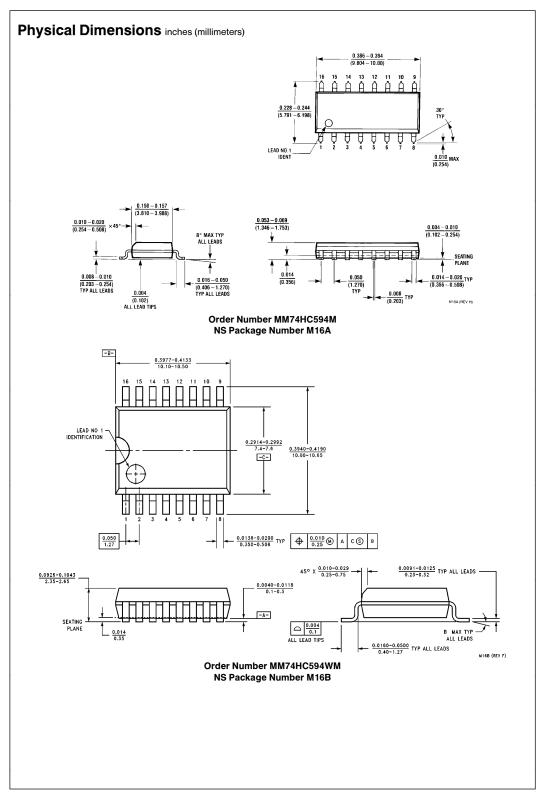
t_{THL}, t_{TLH}

 C_{PD}

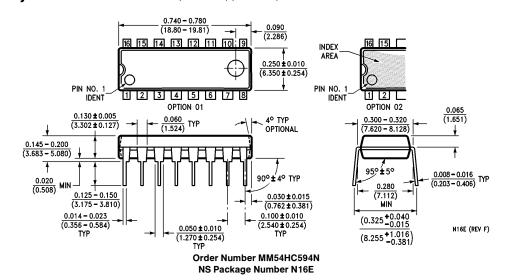
 C_{IN}

COUT





Physical Dimensions inches (millimeters) (Continued)



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